#### 501794631 01/23/2012

#### PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
Sadayuki Kobayashi	01/13/2012
Shinichiro Ochiai	01/13/2012

### RECEIVING PARTY DATA

Name:	Toray Industries, Inc.	
Street Address:	1-1, Nihonbashi-Muromachi 2-chome	
Internal Address:	Chuo-ku	
City:	Tokyo	
State/Country:	JAPAN	
Postal Code:	103-8666	

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13386511

### **CORRESPONDENCE DATA**

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Address Line 4: PHILADELPHIA, PENNSYLVANIA 19103

ATTORNEY DOCKET NUMBER:	TIP-11-1461
NAME OF SUBMITTER:	Leslie J. Hood

**Total Attachments: 1** 

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PATENT REEL: 027576 FRAME: 0485

# ASSIGNMENT

WHEREAS, we, Sadayuki Kobayashi and Shinichiro Ochiai, citizens of Japan, both residing at c/o Nagova Plant, Toray Industries, Inc., 9-1, Oe-cho, Minato-ku, Nagoya-shi, Aichi 4558502 Japan, (hereinafter referred to as "the undersigned"), having made an invention entitled POLYMER ALLOY, PROCESS FOR PRODUCING SAME, AND MOLDED ARTICLE, identified in International Application No. PCT/JP2010/061941, and in US Application No. 13/386,511 (DLA Piper is authorized to insert the Serial No. when known),

WHEREAS, Toray Industries, Inc., with offices located at 1-1, Nihonbashi-Muromachi 2chome, Chuo-ku, Tokyo 1038666, Japan (hereinafter referred to as "the assignee"), is desirous of acquiring the entire right, title and interest in said invention, said US application and all letters patent issuing for said invention.

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and of other good and valuable consideration, receipt of which is hereby acknowledged, the undersigned, intending to be legally bound, do hereby sell, assign and transfer to the assignee the entire right, title and interest, for the United States of America, its territories and possessions, and for all foreign countries, in said invention, including said US application, all divisions and continuations thereof, all rights to claim priority based thereon, all rights to file foreign applications on said invention, and all letters patent and reissues thereof, issuing for said invention in the United States of America and in any and all foreign countries.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the undersigned has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the assignee, and to execute all instruments proper to carry out the intent of this instrument. If the undersigned includes more than one individual, these obligations shall apply to all of the undersigned both individually and collectively.

The rights and property herein conveyed by the undersigned are free and clear of any encumbrance.

**EXECUTED** on the date(s) set forth below.

Jan. 13, 20/2 Date

Jan. 13, 20/2
Date

Sadayuki Kobayashi

Shinichiro Ochiai

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**PATENT REEL: 027576 FRAME: 0486**